

**IN THE SPECIFICATION:**

Amend the third full paragraph on page 7 as follows:

*B1*  
As can be seen from Fig. [[1]] 3, the etching rate for the thermal oxide film remarkably increases with the lapse of time.

Amend the paragraph beginning on line 22 of page 13 as follows:

*B2*  
As mentioned above, by adding to the cleaning liquid water, aqueous ammonia, or an aqueous solution of ammonium fluoride in consideration of the etching rate and the individual component concentrations of the cleaning liquid at a certain point in time in the treatment, the etching treatment by the cleaning liquid can be conducted uniformly and stably (namely, the etching rate for an oxide film can be kept constant), so that there is no need to frequently replace the cleaning liquid, which differs differing from the conventional cleaning. Therefore, the ~~life-time~~ lifetime of the cleaning liquid can be prolonged, and the reduction in frequency of the liquid replacement contributes to a reduction in the cleaning liquid consumed (resource saving) and a reduction in the waste water treatment agent required for the waste water treatment of the cleaning liquid (resource saving). Further, the reduction in these chemicals used contributes to a reduction in the amount of sludge and waste water produced upon the waste water treatment (reduction in the amount of waste).